

Industry Sessions for Transducers 2017

Date	Theme and Program	
June 18	Theme: Start-up	
13:00-13:10	Opening Mr. Terry Tsao, President, SEMI Taiwan	
13:10-13:40	Title: MEMS & Sensors industry trends Ms. Claire Troadec, MEMS and Semiconductor Analyst, Yole	
13:40-14:10	Title: How MEMS and Entrepreneurs are Driving IoT Dr. Kurt Petersen, Co-founder of NovaSensor , Cepheid , SiTime , etc. (USA)	
14:10-14:40	Title: MEMS Startups – West and East, Then and Now Dr. Wan-Thai Hsu, Co-founder of Discera (USA)	
14:40-15:10	Title: poLight TLens - a high performance Piezo MEMS AF tech ready for MP Mr. Pierre Craen, Chief Technology Officer, poLight (Norway)	
15:10-15:30	Break	
June 18	Theme: IoT	
15:30-16:00	Title: The IoT system challenge Mr. Leopold Beer, Asia Regional President, BOSCH Sensortec	
16:00-16:30	Title: Environmental monitoring with low cost sensor networks Dr. Frank Pasveer, Program Manager IoT, imec	
16:30-17:00	Title: City of tomorrow: smart mobility for a sustainable future Mr. John Lin, Vice President, FORD (Lio Ho)	
17:00-17:40	Panel Discussion	
June 19	Theme: IDM	
12:30-13:00	Title: Mr. Giuseppe Izzo, Managing Director, ST Microelectronics	
13:00-13:30	Title: MEMS technologies evolve automobiles!? Dr. Nobuaki Kawahara, Head of Research Lab., DENSO	
13:30-14:00	Title: FBAR impact on mobile phones Dr. Richard Ruby, Director of Technology, BROADCOM	
June 20	Theme: Fab	
12:30-12:55	Title: Process module & big data assisted manufacturing: fast time-to-production Dr. Jerwei Hsieh, Vice President, apm	
12:55-13:20	Title: Fab IT Support Systems and Protocols for successful MEMS process transfers Mr. Tomas Bauer, Senior Vice President, Silex	
13:20-13:45	Title: Challenge/Opportunity of 200/300mm More-than-Moore tech. transitions Dr. Mike Rosa, Head of Marketing for EPG, Applied Materials	
13:45-14:10	Title: Variety of materials handling for MEMS fab Mr. Wilbur Catabay, Senior Vice President, TSI Semiconductors	
June 21	Theme: Packaging/Testing	
12:30-12:55	Title: New wave miniaturized SiP Dr. Vincent Lin, Director of Advanced Technology, ASE Group	
12:55-13:20	Title: MEMS wafer-level test and WLCSP final test: requirements and solutions Mr. Emanuele Bardo, Manager, SPEA	
13:20-13:45	Title: Advances in aligned wafer bonding enabled by ultra high vacuum processing Dr. Bernhard Rebhan, Senior Scientist of Tech. Development Dept., EVG	
13:45-14:10	Title: Reaching the lowest MEMS test cost using Probers with physical stimulus Mr. Ari Kuukkala, Business Development Director, AFORE	

Note: Complimentary lunch boxes on June 19-21 will be provided during Industry Sessions